

Basic information	
2018/2947(DEA) DEA - Delegated acts procedure	Procedure completed - delegated act enters into force
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages Supplementing 2008/0240(COD) Subject 3.40.06 Electronics, electrotechnical industries, ICT, robotics 3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)	

Documentation gateway			
European Commission			
Document type	Reference	Date	Summary
Non-legislative basic document	C(2018)07499	16/11/2018	
Document attached to the procedure	C(2025)5889	25/08/2025	